

## Amendments to Claims

1. (Currently Amended) A circuit, comprising:  
electronic component;  
structure that is disposed onto an enclosure for the electronic component and that is provided to reduce a ~~for~~ reducing thermal drift in at least one characteristic of the electronic component by increasing a thermal mass of the electronic component.
2. (Cancelled) The circuit of claim 1, wherein the structure comprises a material that increases a thermal mass of the electronic component.
3. (Currently Amended) The circuit of claim 1 ~~claim 2~~, wherein the ~~material~~ structure comprises a metal case around the electronic component.
4. (Currently Amended) The circuit of claim 1 ~~claim 2~~, wherein the ~~material~~ structure comprises a ceramic case around the electronic component.
5. (Cancelled) The circuit of claim 1, wherein the structure comprises an insulator.
6. (Currently Amended) The circuit of claim 1, wherein the structure comprises a material that increases a the thermal mass of the electronic component and an insulator that encases the electronic component and the material.
7. (Cancelled) The circuit of claim 1, wherein the structure comprises a circuit board that holds the electronic component which is separated from a circuit board that holds a set of other components of the circuit.

8. (Cancelled) The circuit of claim 7, wherein the structure further comprises a material that increases a thermal mass of the electronic component.
9. (Cancelled) The circuit of claim 7, wherein the structure further comprises an insulator over the electronic component.
10. (Cancelled) The circuit of claim 7, wherein the structure further comprises a material that increases a thermal mass of the electronic component and an insulator that encases the electronic component and the material.
11. (Cancelled) The circuit of claim 1, wherein the structure comprises a gap which reduces a heat conduction path a ground plane in a circuit board and the electronic component.
12. (Original) The circuit of claim 1, wherein the circuit is an oscillator circuit.
13. (Original) The circuit of claim 1, wherein the circuit is a clock circuit.
14. (Currently Amended) The circuit of claim 13 ~~12~~, further comprising:  
    means for communication via a network;  
    means for synchronizing a local time value in the clock circuit in response to a set of messages transferred via the network.
15. (Currently Amended) A distributed system having a set of nodes, each node comprising:  
    local clock including a crystal component;

structure for reducing thermal drift in the electronic crystal component by increasing a thermal mass of the crystal component.

16. (Cancelled) The distributed system of claim 15, wherein the structure comprises a material that increases a thermal mass of the electronic component.

17. (Currently Amended) The distributed system of claim 15 ~~16~~, wherein the ~~material~~ structure comprises a metal case around the ~~electronic~~ crystal component.

18. (Currently Amended) The distributed system of claim 15 ~~16~~, wherein the ~~material~~ structure comprises a ceramic case around the ~~electronic~~ crystal component.

19. (Cancelled) The distributed system of claim 15, wherein the structure comprises an insulator.

20. (Currently Amended) The distributed system of claim 15, wherein the structure comprises a material that increases a thermal mass of the ~~electronic~~ crystal component and an insulator that encases the ~~electronic~~ crystal component and the material.

21. (New) A circuit, comprising:  
    electronic component;  
    structure for thermally isolating the electronic component from a set of other components of the circuit.

22. (New) The circuit of claim 21, wherein the structure comprises a circuit board that holds the electronic component and that is separated from a circuit board that holds the other components of the circuit.

23. (New) The circuit of claim 22, wherein the structure further comprises a material that increases a thermal mass of the electronic component.

24. (New) The circuit of claim 22, wherein the structure further comprises an insulator over the electronic component.

25. (New) The circuit of claim 22, wherein the structure further comprises a material that increases a thermal mass of the electronic component and an insulator that encases the electronic component and the material.

26. (New) The circuit of claim 21, wherein the structure comprises a gap in a ground plane of a circuit board that holds the electronic component and the other components and which reduces a heat conduction path between the ground plane and the electronic component.